

IN THE CLAIMS:

Please CANCEL claims 1-21 ~~without~~ prejudice to or disclaimer of the recited subject matter.

Please ADD new claims 22-37, as follows. Note that all the claims currently pending in this application, including those not currently amended, have been reproduced below for the Examiner's convenience.

---

1-21. (Cancelled)

C'

22. (New) A pod, which has walls and a lid for an opening formed by said walls, and is capable of including a substrate, said pod comprising:

an electromagnetic shield member provided by said walls; and

a flange provided around the opening, which is to contact an electromagnetic-shielded chamber for processing the substrate, at a portion around an opening covered with a lid of the electromagnetic-shielded chamber, and causes said electromagnetic shield member to be grounded through the electromagnetic-shielded chamber.

23. (New) A pod according to Claim 22, wherein said lid of said pod is arranged in front of said pod.

24. (New) A pod according to Claim 22, wherein said lid of said pod is arranged in a bottom of said pod.

C1  
cont.

25. (New) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh provided on or within said walls.

26. (New) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings provided on said walls.

27. (New) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials provided in said walls.

28. (New) A micro-device manufacturing apparatus using a substrate, said apparatus comprising:

an electromagnetic-shielded chamber having an opening covered with a door;

a door-opener which opens said door;

a processing system, contained in said electromagnetic-shielded chamber, which processes the substrate; and

a stand which mounts a pod, wherein said pod has walls and a lid for an opening formed by said walls, and is capable of including the substrate, said pod comprising:

C1  
cont.

- (i) an electromagnetic shield member provided by said walls; and
- (ii) a flange provided around the opening of said pod, which is to contact said electromagnetic-shielded chamber at a portion around said opening of said electromagnetic-shielded chamber, and causes said electromagnetic shield member to be grounded through said electromagnetic-shielded chamber.

29. (New) An apparatus according to claim 28, wherein said electromagnetic-shielded chamber has a grounded portion around said opening of said electromagnetic-shielded chamber, which contacts said flange of said pod.

30. (New) An apparatus according to Claim 28, wherein said processing system exposes the substrate to radiation.

31. (New) An apparatus according to Claim 28, wherein said lid of said pod is arranged in front of said pod.

32. (New) An apparatus according to Claim 28, wherein said lid of said pod is arranged in a bottom of said pod.

33. (New) An apparatus according to Claim 28, wherein said electromagnetic shield member comprises wire mesh provided on or within said walls.

34. (New) An apparatus according to Claim 28, wherein said electromagnetic shield member comprises metal coatings provided on said walls.

35. (New) An apparatus according to Claim 28, wherein said electromagnetic shield member comprises electromagnetic-shield materials provided in said walls.

C1  
Cont.

36. (New) A micro-device manufacturing method using a substrate, said method comprising the steps of:

providing a micro-device manufacturing apparatus using a substrate, which comprises (i) an electromagnetic-shielded chamber having an opening covered with a door, (ii) a door opener which opens the door, (iii) a processing system, contained in the electromagnetic-shielded chamber, which processes the substrate, and (iv) a stand which mounts a pod;

providing the pod, which has walls and a lid for an opening formed by the walls, is capable of including the substrate and comprises (i) an electromagnetic shield member provided by the walls and (ii) a flange provided around the opening of the pod, which is to contact the electromagnetic-shielded chamber at a portion around the opening of the electromagnetic-shielded chamber, and causes the electromagnetic shield member to be grounded through the electromagnetic-shielded chamber;

installing the pod on the stand of the micro-device manufacturing apparatus;

opening both the door of the micro-device manufacturing apparatus and the lid of the pod;

transferring the substrate in the pod to the processing system; and  
processing the substrate with the processing system.

CI  
concluded

37. (New) A method according to Claim 36, wherein, in said processing step, the  
substrate is exposed to radiation.

---